

# DATICS-ICMS'09: Design, Analysis and Tools for Integrated Circuits and Systems

The *International Workshop DATICS-ICMS'09: Design, Analysis and Tools for Integrated Circuits and Systems* in the International Conference of Mathematical Sciences (ICMS 2009) will take place in Istanbul, Turkey, 4-10, August, 2009.

The main target of the DATICS-ICMS'09 is to bring together software/hardware engineering researchers, computer scientists, practitioners and people from industry to exchange theories, ideas, techniques and experiences related to all areas of design, analysis and tools for integrated circuits (e.g. digital, analog and mixed-signal circuits) and systems (e.g. real-time, hybrid and embedded systems). DATICS-ICMS'09 also focuses on the fields of formal methods, low power design methodologies for integrated circuits and wireless sensor networks (WSNs).

The *International Program Committee* (IPC) of DATICS-ICMS'09 consists of about 80 experts in the related fields of DATICS-ICMS'09 both from academia and industry. DATICS-ICMS'09 is partnered with CEOL: Centre for Efficiency-Oriented Languages (Ireland), International Software and Productivity Engineering Institute (USA), Intelligent Support Ltd., (United Kingdom), Minteos (Italy), M.O.S.T. (Italy), Electronic Center (Italy) and Legale Fiscale (Italy). DATICS-ICMS'09 is sponsored by LS Industrial Systems (South Korea) and Solari (Hong Kong).

DATICS-ICMS'09 received 26 full-paper submissions from 11 different countries around the world. These submissions were sent to the members of the IPC and additional reviewers for review. Every submission received at least two independent reviews. We would like to thank the IPC members and the reviewers for their hard work and dedication. The DATICS-ICMS'09 Technical Program includes 10 papers (acceptance rate of 39%) which are organised into lecture sessions.

On behalf of the IPC, we would like to welcome the delegates and their guests to the DATICS-ICMS'09. We hope that you will enjoy the workshop and find the DATICS-ICMS'09 Technical Program exciting.

*Ka Lok Man and Michele Mercaldi - DATICS-ICMS'09, IPC Chairs*

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